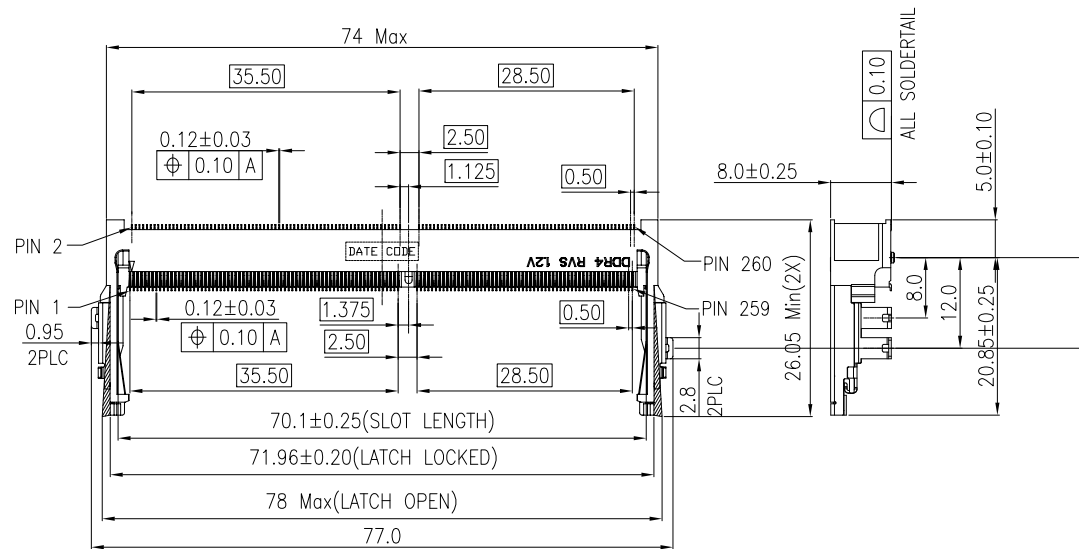


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/11/02	Phebe Su



NOTES:

1.MATERIAL:

- 1.1 HOUSING: LCP, UL94V-0, COLOR: BLACK.
- 1.2 CONTACT: PHOSPHOR BRONZE.
- 1.3 SOLDER PEG AND LATCH: STAINLESS STEEL.

2. FINISH:

- 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER.
GOLD FLASH PLATING ON SOLDER TAIL.
GOLD PLATING (THICKNESS SEE TABLE) ON CONTACT AREA.
- 2.2 SOLDER PEG:
50u" MIN NICKEL UNDERPLATED ALL OVER.
AU 2u" MAX ON SOLDER TAIL.

3. DATE CODE : YYWWDLX

YY: YEAR (09: 2009)
WW: WEEK (25: THE 25TH WEEK)
D: DAY (1~7: SUNDAY~SATURDAY)
L: LINE NUMBER OF ASSEMBLY (A: LINE A)
X: D OR N (D: DAY; N: NIGHT)

4. PART NUMBER DESCRIPTION:

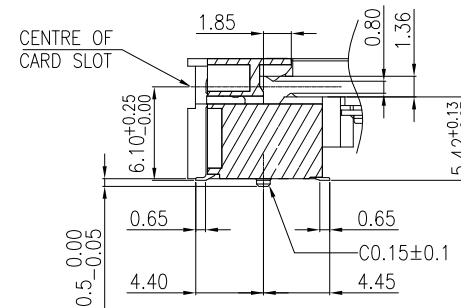
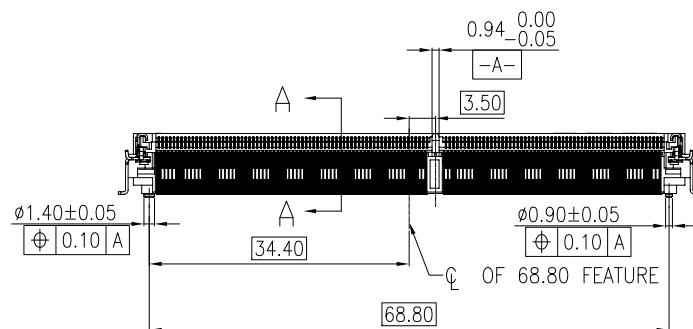
MDDR4-260X19

Series number

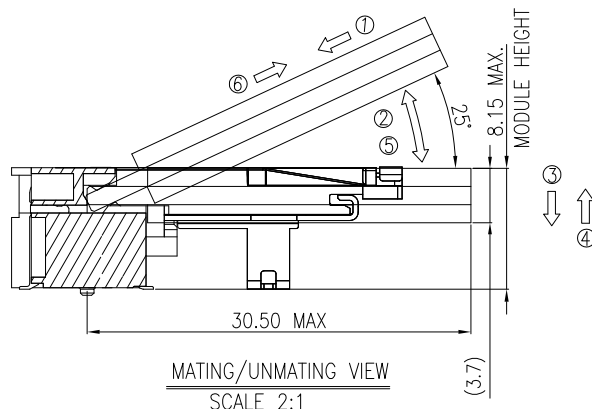
PLATING CODE:

1: GF 2: Au5u" 3: Au10u"
4: Au15u" 5: Au30u"

PIN NUMBER CODE: 260 PINS



SECTION: A-A
SCALE 2:1

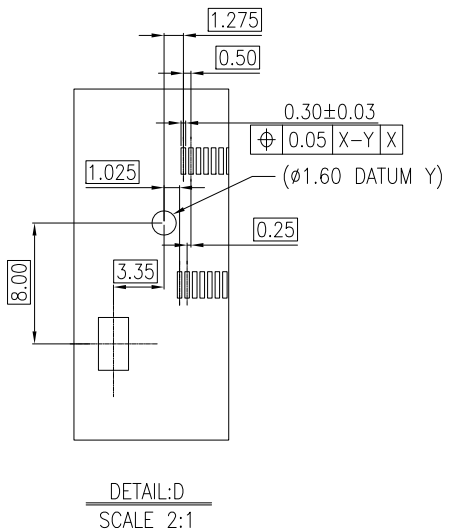
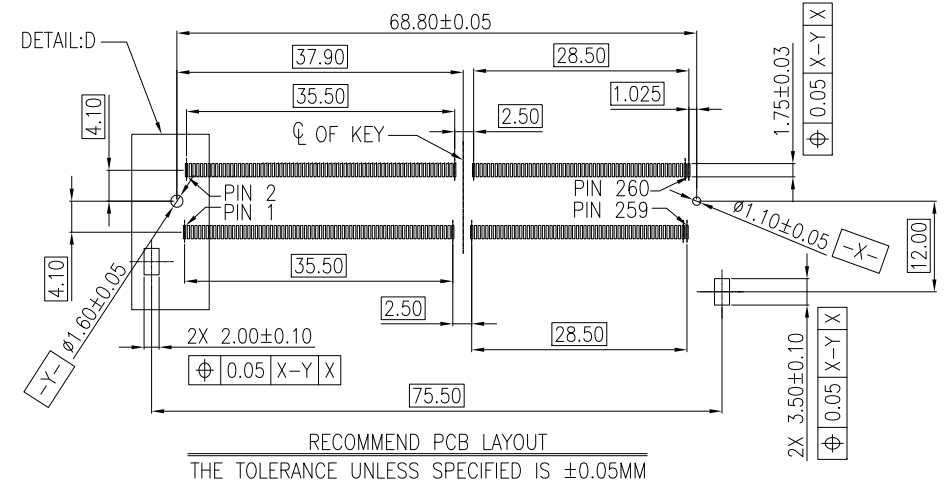
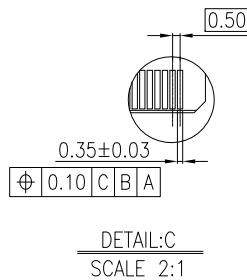
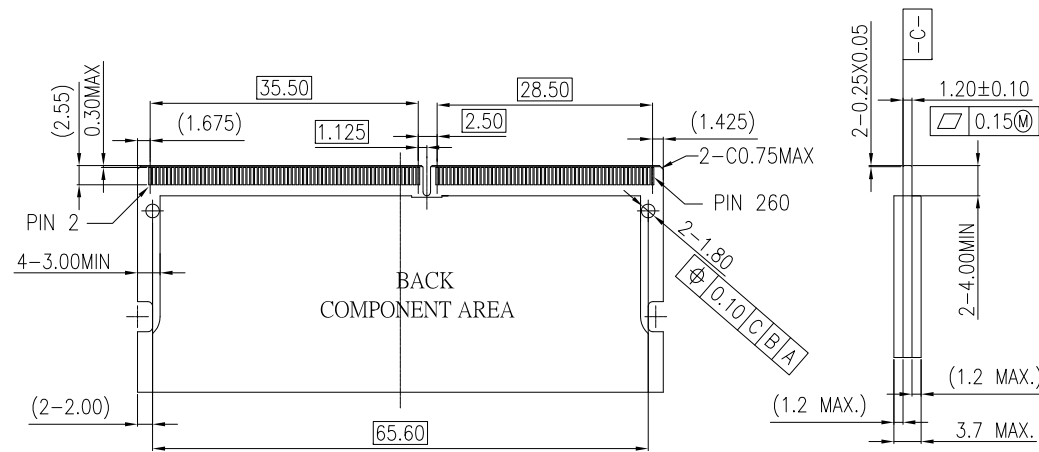
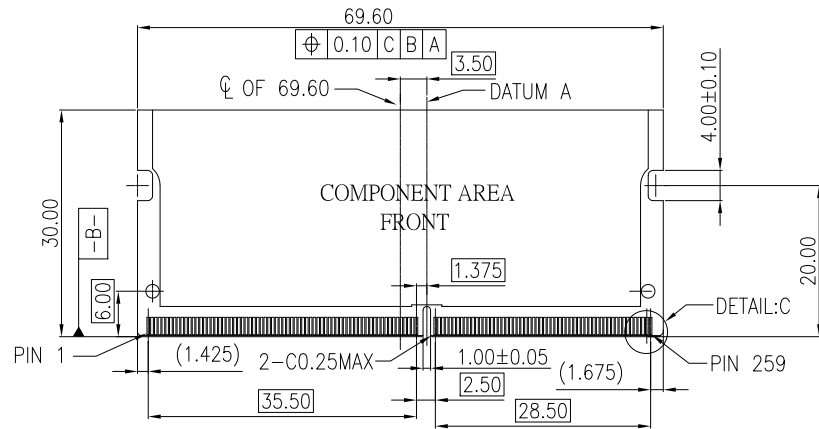


MATING: ① INSERTING(30°) → ② ROTATING → ③ FIXED
UNMATING: ④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING

NO	VARIETY	QTY	METERIAL	REMARK
			Matrix Electronics Co.,Ltd	
TOLERANCE:		DESIGN BY :	DATE :	PART NAME:
X:X ±0.25		Phebe Su	2015/11/02	DDR4 SO DIMM 8.0H RVS
X:XX ±0.15		CHECKED BY:	DATE :	PART NO.
X:XXX ±0.10		Vicky Hsieh	2015/11/02	MDDR4-260X19
ANGLE: ±3°		APPROVED BY1:	DATE :	MOLD NO.
		Richard Hsieh	2015/11/02	NA
UNIT: mm [inch]		APPROVED BY2:	DATE :	DRAW NO.
SCALE:1:1		Richard Hsieh	2015/11/02	SHEET NO.
SIZE:A4				1 OF 2

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/11/02	Phebe Su



NO	VARIETY	QTY	METERIAL	REMARK
			Matrix Electronics Co.,Ltd	
TOLERANCE:		DESIGN BY :	DATE :	PART NAME:
X:X ±0.25		Phebe Su	2015/11/02	DDR4 SO DIMM 8.0H RVS
X:XX ±0.15		CHECKED BY:	DATE :	PART NO.
X:XXX ±0.10		Vicky Hsieh	2015/11/02	MDDR4-260X19
ANGLE: ±3°		APPROVED BY1:	DATE :	MOLD NO.
		Richard Hsieh	2015/11/02	NA
UNIT: mm [inch]		APPROVED BY2:	DATE :	DRAW NO.
SCALE:1:1 SIZE:A4		Richard Hsieh	2015/11/02	SHEET NO.
				2 OF 2